

ABSTRACT

MASK MATERIAL FOR PLASMA DICING, MASK-INTEGRATED SURFACE
PROTECTIVE TAPE AND METHOD OF PRODUCING SEMICONDUCTOR

5 CHIP

A mask material for plasma dicing, which is used in a plasma step, whose
surface roughness Rz at the surface side that does not touch with an adherend is
from 0.1 μm to 1.5 μm ;

10 a mask-integrated surface protective tape; and
a method of producing a semiconductor chip.

(Fig. 4)